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Bib Data Sheet

## **CONFIRMATION NO. 5090**

Christophe Maleville, La Terrasse, FRANCE; Corinne Maunand Tussot, Meylan, FRANCE;  "CONTINUING DATA											
Christophe Maleville, La Terrasse, FRANCE; Corinne Maunand Tussot, Meylan, FRANCE;  "CONTINUING DATA		NUMBER 03/25/2004 CI 08,288					DOCKET NO.				
Corinne Maunand Tussot, Meylan, FRANCE;  ***CONTINUING DATA ****  This appln claims benefit of 60/489,275 07/22/2003  ***FOREIGN APPLICATIONS **** FRANCE 0303699 03/26/2003  IF REQUIRED, FOREIGN FILING LICENSE GRANTED ***06/05/2004  Foreign Priority claimed *** **Super Line of the Country o	APPLICANTS										
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